

ExpressPort® SFP+

Amphenol ICC's ExpressPort® SFP+ interconnect system provides data transfer speeds of up to 16Gb/s. The design of the ExpressPort® SFP+ connector minimizes impedance discontinuities and reflections at high data rates and provides a 10 to 20 dB improvement in Near-End Crosstalk. The ExpressPort® SFP+ unique cage construction features EMI shielding available in the form of metal spring fingers or elastomeric gaskets. Additional features available include light pipes, heat sinks and many other custom features.



TECHNICAL INFORMATION

MATERIAL

- Housing: Black or nature color, Glass-reinforced, lead-free solder reflow process compatible thermoplastic
- Contacts Base Material: Phosphor Bronze
- Plating Solder Tails: Matte tin or gold flash options
- Plating Mating Area: Gold
- Resonance Dampening Feature: Conductive Polymer

MECHANICAL PERFORMANCE

- Durability: 250 mating cycles
- Mating Force: 50 N max.
- Card Entry Slot: 1.0mm-thick integrated circuit
- Contact Normal Force: 100 grams
- PCB Thickness Single Side (Cage): 1.57 mm (0.062 in.) min.
- PCB Thickness Belly to Belly (Cage): 3.00 mm (0.118 in.) min.
- Unmating Force (Cage): 11.50 N max.
- Insertion Force to PCB (Cage):
- 1000 N for 2 port
- 2100 N for 4 port
- 3000 N for 6 port

ELECTRICAL PERFORMANCE

- Operating Voltage: 30 VDC per contact
- Operating Current: 0.5 A per contact
- Differential Impedance: $100\Omega + /- 10\Omega$

ENVIRONMENTAL

- Operating and (Storage) Temperature: -55° to +85°C
- RoHS & Halogen-Free

TOOLING INFORMATION

- EMI Options, Heat Sink and Clip: Available
- Configurations:
- 1xN (N = 1,2,3,4,5,6,8)
- 2xN (N = 1,2,3,4,5,6,8)

TARGET MARKETS/APPLICATIONS



Cellular Infrastructure Network Interface Cards Switch



Hubs Servers

Storage



Test and Measurement Equipment

ExpressPort® SFP+

ExpressPort® SFP+ Connector







